

**REMARKS**

Claims 11 to 14 and 21 were rejected under 35 U.S.C. §102 as being anticipated by DE 197 20 652. Claims 15 and 16 were rejected under 35 U.S.C. §103(a) as being unpatentable over DE 197 20 652 and further in view of JP 40-7185852. Claims 17 to 20 were rejected under 35 U.S.C. §103(a) as being unpatentable over DE 197 20 652 and further in view of US 2008/0053972 (Otsu et al.). Claim 21 was rejected under 35 U.S.C. §103(a) as being unpatentable over DE 197 20 652 and further in view of KR 2001-068666. Claim 22 was rejected under 35 U.S.C. §103(a) as being unpatentable over DE 197 20 652 in view of Otsu et al. and further in view of KR 2001-068666.

Claim 11 has been amended, and claim 22 canceled without prejudice. Support for the amendment is found in claim 22 for example.

Reconsideration of the application based on the following remarks is respectfully requested.

**Rejection under 35 U.S.C. 102**

Claims 11 to 14 and 21 were rejected under 35 U.S.C. §102 as being anticipated by DE 197 20 652. In view of the amendment to claim 11, withdrawal of the rejection of claims 11 to 14 and 21 under 35 U.S.C. §102 is respectfully requested.

**Rejection under 35 U.S.C. 103(a)**

Claims 15 and 16 were rejected under 35 U.S.C. §103(a) as being unpatentable over DE 197 20 652 and further in view of JP 40-7185852. Claims 17 to 20 were rejected under 35 U.S.C. §103(a) as being unpatentable over DE 197 20 652 and further in view of US 2008/0053972 (Otsu et al.). Claim 21 was rejected under 35 U.S.C. §103(a) as being unpatentable over DE 197 20 652 and further in view of KR 2001-068666. Claim 22 was rejected under 35 U.S.C. §103(a) as being unpatentable over DE 197 20 652 in view of Otsu et al. and further in view of KR 2001-068666.

DE '652 discloses heating with a plurality of laser sources. Otsu discloses processing brittle material. KR '666 discloses a laser hardfacing head.

Claim 11 now recites "A method for processing one or more components of gas turbines, comprising:

heating a component of a gas turbine with at least one laser device; and  
laser hardfacing the component with a separate laser device, the heating occurring prior to and/or during the laser hardfacing."

It is respectfully submitted that DE '652 in combination with Otsu and KR '666 (even if properly combinable, which it is respectfully submitted, they are not) does not teach or disclose using two separate laser devices, one for heating and another for laser hardfacing.

Moreover, DE '652 in combination with Otsu and KR '666 (even if properly combinable, which it is respectfully submitted they are not) does not teach or disclose that the heating with the at least laser device occurs "prior to and/or during the laser hardfacing" as now claimed.

Withdrawal of the rejection of pending claims 11 to 21 under 35 U.S.C. 103(a) is respectfully requested.

In addition, the dependent claims are now respectfully submitted as being patentable as they depend from amended claim 11.

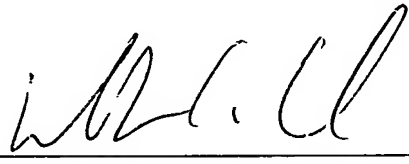
**CONCLUSION**

It is respectfully submitted that the application is in condition for allowance and applicants respectfully request such action.

If any additional fees are deemed to be due at this time, the Assistant Commissioner is authorized to charge payment of the same to Deposit Account No. 50-0552.

Respectfully submitted,

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